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## 2014 - April

# Specification for Base Materials for Rigid and Multilayer Printed Boards

Supersedes IPC-4101C
April 2009

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# IPC-4101D

# Specification for Base Materials for Rigid and Multilayer Printed Boards

Developed by the Laminate/Prepreg Materials Subcommittee (3-11) of the Printed Board Base Materials Committee (3-10) of IPC

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# Specification for Base Materials for Rigid and Multilayer Printed Boards

## 1 SCOPE

This specification covers the requirements for base materials, herein referred to as laminate or prepreg, to be used primarily for rigid or multilayer printed boards for electrical and electronic circuits.

**1.1 Classification** The system shown below identifies clad and unclad laminate or prepreg base materials. The specification sheets serve as a cross-reference connecting the outlined callout system in this document to previously used systems.

Example for laminate base materials where this specification is referenced:

| | |
|---|---|
| L | Material Designator (see 1.1.1) |
| 25 | Specification Sheet Number (see 1.1.1) |
| 1500 | Nominal Laminate Thickness (see 1.1.2) |
| C1/C1 | Metal Cladding Type and Nominal Weight/Thickness (see 1.1.3) |
| A | Thickness Tolerance Class (see 1.1.4) |
| A | Surface Quality Class (see 1.1.5) |

Example for prepreg base materials where this specification is referenced:

| | |
|---|---|
| P | Material Designator (see 1.1.1) |
| 25 | Specification Sheet Number (see 1.1.1) |
| E7628 | Reinforcement Style (see 1.1.6) |
| TW | Resin Content Method (see 1.1.7) |
| RE | Flow Parameter Method (see 1.1.7) |
| VC | Optional Prepreg Method (see 1.1.7) |

**1.1.1 Specification Sheet Description** At the end of this document is a series of specification sheets. Each specification sheet outlines requirements for both laminate and prepreg for each product grade. The specification sheets are organized by a specific reinforcement type, resin system, and/or construction and are provided with a specification sheet number for ordering purposes. For convenience, the laminate and prepreg requirements for materials of the like composition are on the same specification sheet. Material Designator ''L'' indicates laminate material and Material Designator ''P'' indicates prepreg material as shown in designation examples in 1.1. When certifying to multiple specification sheets, the strongest performance requirements **shall** apply.

The headings for each specification sheet include reference definitions for the material, which cover the reinforcements, resin systems, flame retardants, and fillers used, as well as its other known identifications and glass transition temperature, $T_g$. The specific line items within the specification sheets are the requirements that material **shall** meet in order to be certified to this specification.

**1.1.2 Nominal Laminate Thickness** The nominal thickness is identified by four digits. For all substrates covered by this document, thicknesses may be specified or measured either over the cladding or over the dielectric (see 1.1.4 and 3.8.4.2). For metric specification, the first digit represents whole millimeters, the second represents tenths of millimeters, etc. For orders requiring Imperial units, the four digits indicate the thickness in ten-thousandths of an inch. In the example shown in 1.1, 1500 designates a laminate with thickness of 1.5 mm [0.0591 in], which would be specified as 0591 when using Imperial units.

**1.1.3 Metal Cladding Type and Nominal Weight/Thickness** The type and nominal weight or thickness of the metallic cladding for laminate base material is identified by five designators. The first and fourth designators indicate the type of cladding; the third designator is a slash mark that differentiates sides of the base material; the second and fifth designators indicate the nominal weight or thickness of the metallic cladding.